

Reference Only

Spec. No. JENF243A-9124A-01

P.1/8

GHz Noise Suppression Chip Ferrite Bead BLM18EG□□□□Z1□ Murata Standard Reference Specification [AEC-Q200]

1. Scope

This reference specification applies to Chip Ferrite Bead BLM18EG_□Z Series for Automotive Electronics based on AEC-Q200 except for Power train and Safety.

2. Part Numbering

(ex.) $\frac{BL}{(1)} \frac{M}{(2)} \frac{18}{(3)} \frac{EG}{(4)} \frac{601}{(5)} \frac{S}{(6)} \frac{Z}{(7)} \frac{1}{(8)} \frac{D}{(9)}$

(1)Product ID (2)Type (3)Dimension(LxW) (4)Characteristics (5)Typical Impedance at 100MHz
(6)Performance (7)Category(for Automotive Electronics) (8)Numbers of Circuit
(9)Packaging(D:Taping)

3. Rating

Customer Part Number	MURATA Part Number	Impedance (Ω) (Under Standard Testing Condition) (*1) (refer to below comment)			Rated Current (mA)	DC Resistance (Ω max.) (*1) refer to below comment)		Remark	ESD Rank 2:2kV
		at 100MHz	at 1GHz			Initial Values	Values After Testing		
			Typical						
	BLM18EG101TZ1D	100±25%	80 min.	140	2000	0.045	0.07	For general use (Thin type)	2
	BLM18EG221TZ1D	220±25%	180 min.	300	1000	0.15	0.21		
	BLM18EG331TZ1D	330±25%	280 min.	450	500	0.21	0.30		
	BLM18EG391TZ1D	390±25%	320 min.	520	500	0.30	0.40		
	BLM18EG121SZ1D	120±25%	90 min.	145	2000	0.04	0.06	For general use	2
	BLM18EG221SZ1D	220±25%	160 min.	260	2000	0.05	0.06		
	BLM18EG471SZ1D	470±25%	340 min.	550	500	0.21	0.30		
	BLM18EG601SZ1D	600±25%	450 min.	700	500	0.35	0.45		

• Operating Temperature : -55°C to +125°C • Storage Temperature : -55°C to +125°C

(*1)

Standard Testing Conditions

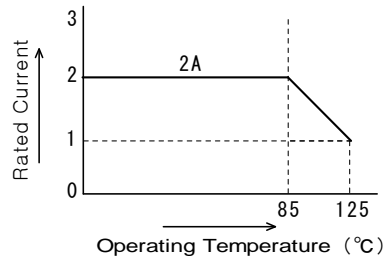
< Unless otherwise specified >

Temperature : Ordinary Temp. (15 °C to 35 °C)
Humidity : Ordinary Humidity (25%(RH) to 85%(RH))

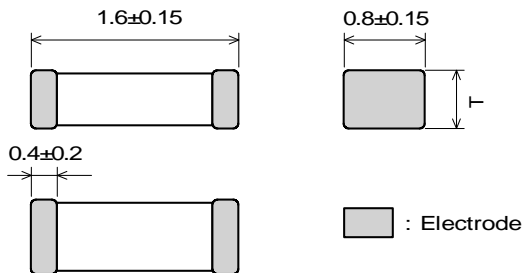
< In case of doubt >

Temperature : 20°C±2 °C
Humidity : 60%(RH) to 70%(RH)
Atmospheric pressure : 86kPa to 106kPa

As for BLM18EG type, Rated Current is derated as right figure depending on the operating temperature.



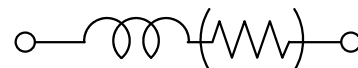
4. Style and Dimensions



Part Number	Dimension(T)
BLM18EG***TZ1	0.5±0.15
BLM18EG***SZ1	0.8±0.15

(in mm)

Equivalent Circuit



(Resistance element becomes dominant at high frequencies.)

Unit Mass (Typical value)

BLM18EG***TZ1 : 0.004g
BLM18EG***SZ1 : 0.005g

Reference Only

Spec. No. JENF243A-9124A-01

P.2/8

5. Marking

No marking.

6. Specifications

6-1. Electrical Performance

No.	Item	Specification	Test Method
6-1-1	Impedance	Meet item 3.	Measuring Frequency : 100MHz±1MHz , 1GHz±1MHz Measuring Equipment : KEYSIGHT 4291A or the equivalent Test Fixture : KEYSIGHT 16192A or the equivalent
6-1-2	DC Resistance	Meet item 3.	Measuring Equipment : Digital multi meter *Except resistance of the Substrate and Wire

6-2. Mechanical Performance(based on Table 13 for FILTER EMI SUPPRESSORS/FILTERS)

AEC-Q200 Rev.D issued June. 1 2010

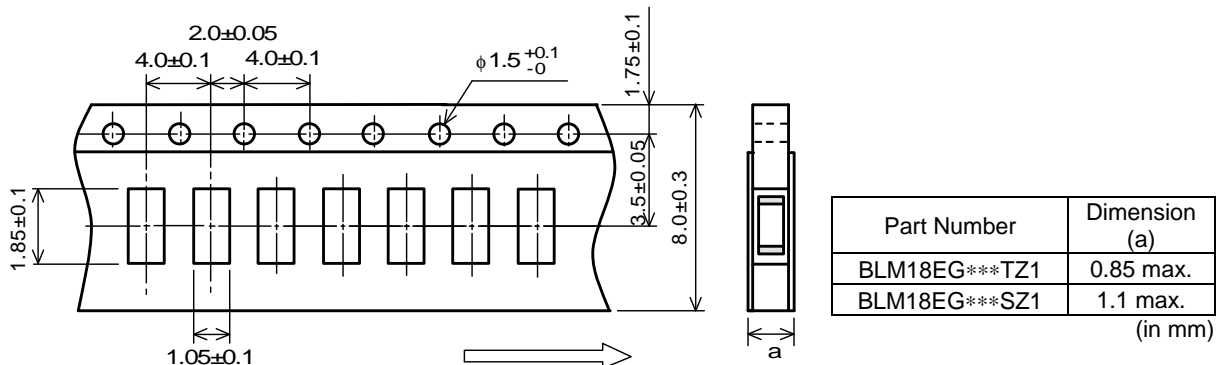
AEC-Q200			Murata Specification / Deviation						
No.	Stress	Test Method							
3	High Temperature Exposure	1000hours at 125 deg C Set for 24hours at room temperature, then measured.	Meet Table A after testing. <u>Table A</u> <table border="1" style="margin-left: 20px;"> <tr> <td>Appearance</td> <td>No damage</td> </tr> <tr> <td>Impedance Change (at 100MHz)</td> <td>Within ±30%</td> </tr> <tr> <td>DC Resistance</td> <td>Meet item 3.</td> </tr> </table>	Appearance	No damage	Impedance Change (at 100MHz)	Within ±30%	DC Resistance	Meet item 3.
Appearance	No damage								
Impedance Change (at 100MHz)	Within ±30%								
DC Resistance	Meet item 3.								
4	Temperature Cycling	1000cycles -55 deg C to +125 deg C Set for 24hours at room temperature, then measured.	Meet Table B. <u>Table B</u> <table border="1" style="margin-left: 20px;"> <tr> <td>Appearance</td> <td>No damage</td> </tr> <tr> <td>Impedance Change (at 100MHz)</td> <td>Within +50%/-10%</td> </tr> <tr> <td>DC Resistance</td> <td>Meet item 3.</td> </tr> </table>	Appearance	No damage	Impedance Change (at 100MHz)	Within +50%/-10%	DC Resistance	Meet item 3.
Appearance	No damage								
Impedance Change (at 100MHz)	Within +50%/-10%								
DC Resistance	Meet item 3.								
5	Destructive Physical Analysis	Per EIA469 No electrical tests	No defects						
7	Biased Humidity	1000hours at 85 deg C, 85%RH Apply max rated current.	Meet Table A after testing.						
9	External Visual	Visual inspection	No abnormalities						
8	Operational Life	Apply 125 deg C 1000hours Set for 24hours at room temperature, then measured	Meet Table A after testing. If the rated current of parts exceed 1A, the operating temperature should be 85 deg C.						
10	Physical Dimension	Meet ITEM 4 (Style and Dimensions)	No defects						
12	Resistance to Solvents	Per MIL-STD-202 Method 215	Not Applicable						
13	Mechanical Shock	Per MIL-STD-202 Method 213 Condition F 1500g's (14.7N)/0.5ms/ Half sine	Meet Table A after testing.						
14	Vibration	5g's(0.049N) for 20 minutes, 12cycles each of 3 orientations Test from 10-2000Hz.	Meet Table A after testing.						
15	Resistance to Soldering Heat	Solder temperature 260C+/-5 deg C Immersion time 10s	Pre-heating:150C +/-10 deg,60s to 90s Meet Table A after testing.						

Reference Only

AEC-Q200			Murata Specification / Deviation
No.	Stress	Test Method	
17	ESD	Per AEC-Q200-002	Meet Table A after testing. ESD Rank: Meet Item 3.(Rating)
18	Solderability	Per J-STD-002	Method b : Not Applicable 95% of the terminations is to be soldered.
19	Electrical Characterization	Measured : Impedance	No defects
20	Flammability	Per UL-94	Not Applicable
21	Board Flex	Epoxy-PCB(1.6mm) Deflection 2mm(min) 60s minimum holding time	Meet Table A after testing.
22	Terminal Strength	Per AEC-Q200-006	No defects
30	Electrical Transient Conduction	Per ISO-7637-2	Not Applicable

7. Specification of Packaging

7-1. Appearance and Dimensions (8mm-wide paper tape)



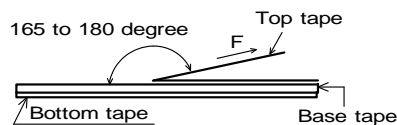
- (1) Taping
Products shall be packaged in the cavity of the base tape of 8mm-wide,4mm-pitch continuously and sealed by top tape and bottom tape.
- (2) Sprocket hole
The sprocket holes are to the right as the tape is pulled toward the user.
- (3) Spliced point
The base tape and top tape have no spliced point
- (4) Cavity
There shall not be burr in the cavity.
- (5) Missing components number
Missing components number within 0.1% of the number per reel or 1 pc., whichever is greater, and are not continuous.The specified quantity per reel is kept.

7-2. Tape Strength

(1) Pull Strength

Top tape	5N min.
Bottom tape	

- (2) Peeling off force of Top tape
0.1N to 0.6N (Minimum value is typical.)
*Speed of Peeling off:300mm/min



8. ⚠ Caution

8-1. Rating

Do not use products beyond the Operating Temperature Range and Rated Current.

8-2. Surge current

Excessive surge current (pulse current or rush current) than specified rated current applied to the product may cause a critical failure, such as an open circuit, burnout caused by excessive temperature rise. Please contact us in advance in case of applying the surge current.

8-3. Fail Safe

Be sure to provide an appropriate fail-safe function on your product to prevent from a second damage that may be caused by the abnormal function or the failure of our products.

8-4. Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

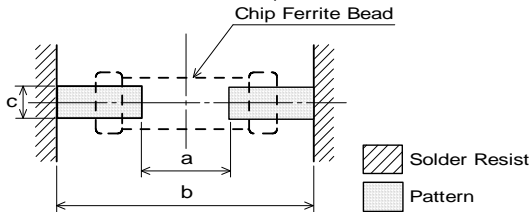
- (1) Aircraft equipment (2) Aerospace equipment (3) Undersea equipment
- (4) Power plant control equipment (5) Medical equipment (6) Disaster prevention / crime prevention equipment
- (7) Traffic signal equipment (8) Transportation equipment (trains, ships, etc.)
- (9) Data-processing equipment
- (10) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

9. Notice

This product is designed for solder mounting. Please consult us in advance for applying other mounting method such as conductive adhesive.

9-1. Land pattern designing

- Standard land dimensions (Flow and Reflow soldering)



Soldering	a	b	c
Flow	0.8	2.5	0.7
Reflow	0.7	2.0	0.7

(in mm)

9-2. Soldering Conditions

Products can be applied to reflow and flow soldering.

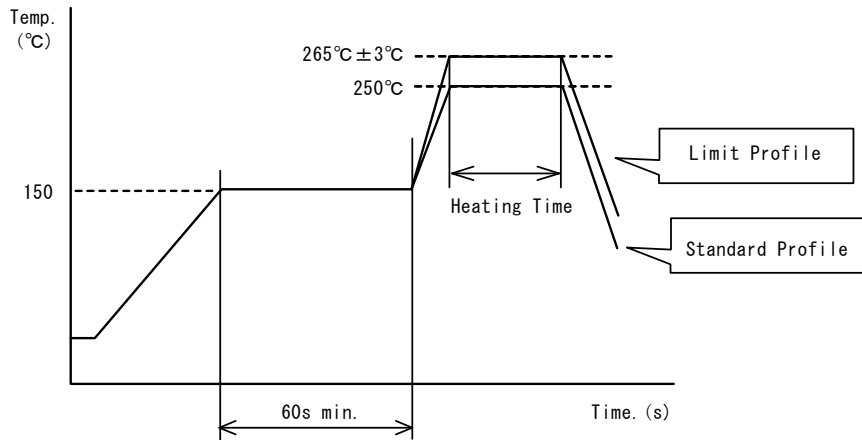
(1) Flux, Solder

Flux	Use rosin-based flux, but not highly acidic flux (with chlorine content exceeding 0.2(wt)%.) Do not use water-soluble flux.
Solder	Use Sn-3.0Ag-0.5Cu solder Standard thickness of solder paste : 100 μm to 200 μm

(2) Soldering conditions

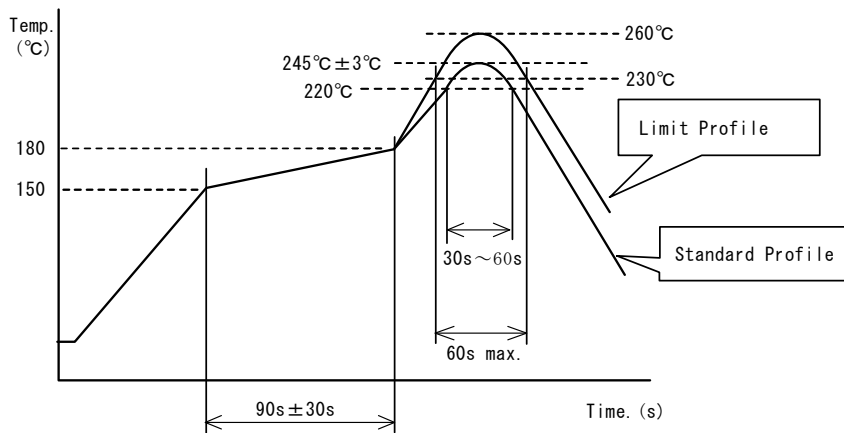
- Pre-heating should be in such a way that the temperature difference between solder and ferrite surface is limited to 150°C max. Also cooling into solvent after soldering should be in such a way that the temperature difference is limited to 100°C max. Insufficient pre-heating may cause cracks on the ferrite, resulting in the deterioration of product quality.
- Standard soldering profile and the limit soldering profile is as follows. The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.

□ Flow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150°C, 60s min.	
Heating	250°C, 4s~6s	265°C±3°C, 5s max.
Cycle of flow	2 times	2 times

□ Reflow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150°C~180°C, 90s±30s	
Heating	above 220°C, 30s~60s	above 230°C, 60s max.
Peak temperature	245°C±3°C	260°C, 10s
Cycle of reflow	2 times	2 times

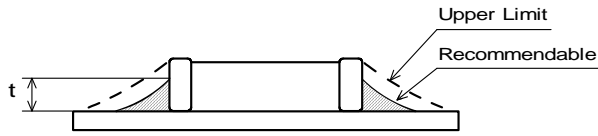
9-3. Reworking with soldering iron

- Pre-heating: 150°C, 1 min
- Tip temperature: 350°C max.
- Soldering time : 3(+1,-0) s
- Soldering iron output: 80W max.
- Tip diameter: φ 3mm max.
- Times : 2times max.

Note : Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the ferrite material due to the thermal shock.

9-4. Solder Volume

Solder shall be used not to be exceeded as shown below.



$$1/3T \leq t \leq T$$

(T:Chip thickness)

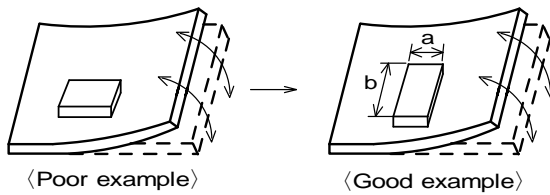
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

9-5. Attention regarding P.C.B. bending

The following shall be considered when designing and laying out P.C.B.'s.

(1) P.C.B. shall be designed so that products are not subject to the mechanical stress for board warpage.

<Products direction>



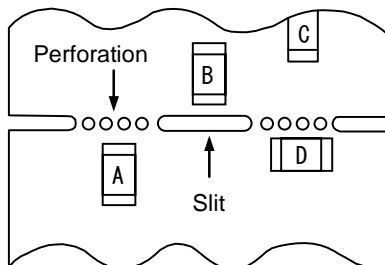
Products shall be located in the sideways direction (Length:a<b) to the mechanical stress.

(2) Components location on P.C.B. separation.

It is effective to implement the following measures, to reduce stress in separating the board.

It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

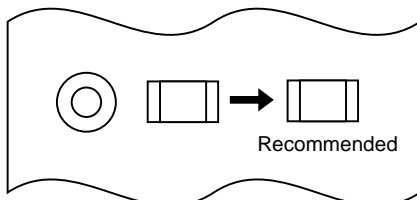
Contents of Measures	Stress Level
(1) Turn the mounting direction of the component parallel to the board separation surface.	A > D *1
(2) Add slits in the board separation part.	A > B
(3) Keep the mounting position of the component away from the board separation surface.	A > C



*1 A > D is valid when stress is added vertically to the perforation as with Hand Separation. If a Cutting Disc is used, stress will be diagonal to the PCB, therefore A > D is invalid.

(3) Mounting Components Near Screw Holes

When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw. Mount the component in a position as far away from the screw holes as possible.



9-6. Mounting density

Add special attention to radiating heat of products when mounting the inductor near the products with heating. The excessive heat by other products may cause deterioration at joint of this product with substrate.